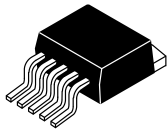
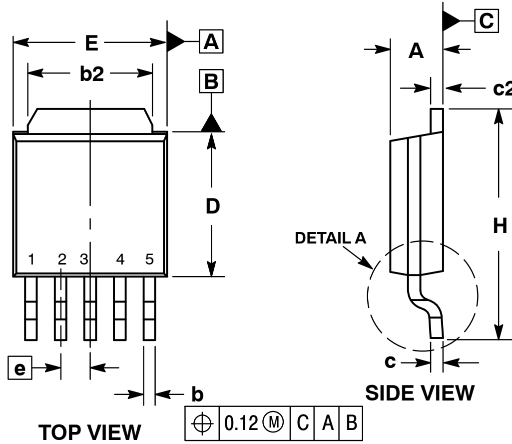


## DPAK−5 (TO−252, 5 LEAD)

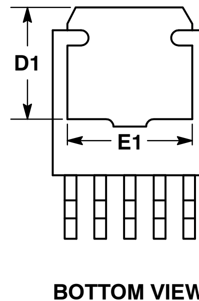
CASE 369AE
ISSUE A

DATE 14 AUG 2013

**SCALE 1:1**




**TOP VIEW**




**SIDE VIEW**

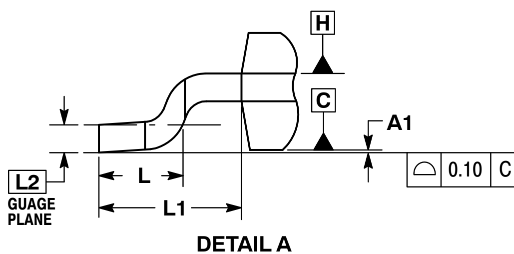
D1

E1

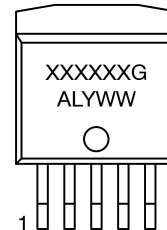
**BOTTOM VIEW**

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL, WITHIN DIMENSIONS SHOWN.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

| DIM | MILLIMETERS MIN | MILLIMETERS MAX |
|---|---|---|
| A | 2.10 | 2.50 |
| A1 | 0.00 | 0.13 |
| b | 0.40 | 0.60 |
| b2 | 5.14 | 5.54 |
| c | 0.40 | 0.60 |
| c2 | 0.40 | 0.60 |
| D | 5.40 | 6.30 |
| D1 | 4.80 | 5.10 |
| E | 6.35 | 6.80 |
| E1 | 4.75 | 5.05 |
| e | 1.27 BSC | |
| H | 9.50 | 10.20 |
| L | 1.39 | 1.78 |
| L1 | 2.50 | 2.90 |
| L2 | 0.51 BSC | |

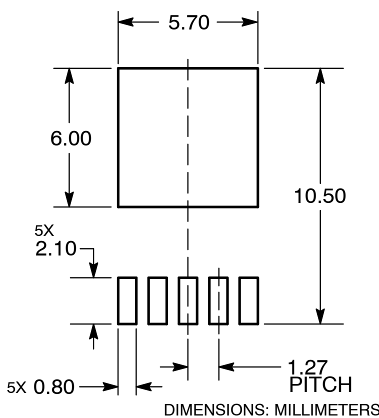



**DETAIL A**




**BOTTOM VIEW**
**ALTERNATE CONSTRUCTION**

**RECOMMENDED SOLDERING FOOTPRINT***




DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM***

XXXXXXG
ALYWW
1

A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

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|---|---|---|
| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | DPAK−5 (TO−252, 5 LEAD) | PAGE 1 OF 2 |

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**DOCUMENT NUMBER:**
**98AON53250E**



| ISSUE | REVISION | DATE |
| --- | --- | --- |
| O | RELEASED FOR PRODUCTION. REQ. BY D. TRUHITTE. | 14 OCT 2010 |
| A | ADDED ADDITIONAL BOTTOM VIEW OPTION. REQ. BY J. LIU. | 14 AUG 2013 |

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